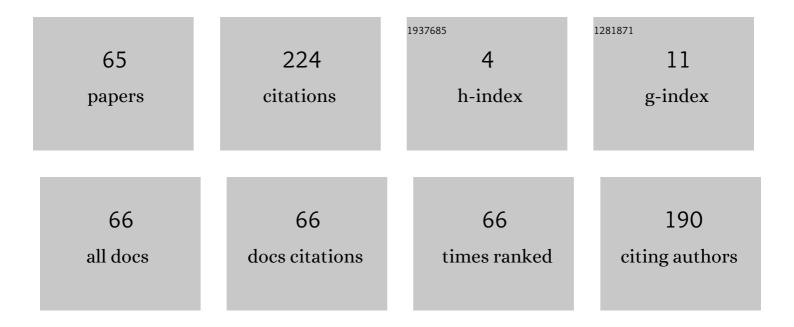
List of Publications by Year in descending order

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Μιμλι Βρληζει

#	Article	IF	CITATIONS
1	Corrosion resistance appraisal of TiN, TiCN and TiAlN coatings deposited by CAE-PVD method on WC–Co cutting tools exposed to artificial sea water. Applied Surface Science, 2015, 358, 572-578.	6.1	52
2	Osseointegration of sputtered SiC-added hydroxyapatite for orthopaedic applications. Ceramics International, 2016, 42, 10085-10093.	4.8	35
3	Phase stability and consolidation of glassy/nanostructured Al85Ni9Nd4Co2 alloys. Journal of Materials Research, 2007, 22, 1145-1155.	2.6	20
4	Lead/Lead Free solder joints comparative shear tests function of working temperature and soldering thermal profile. , 2013, , .		12
5	Lead/lead free solder joints comparative electrical tests as function of microstructure and soldering thermal profile. , 2013, , .		10
6	Correlation between the thermophysical properties, geometry and microstructure of the SAC305 and SAC-X typical solder joints. , 2009, , .		8
7	Mechanical tests regarding low-temperature lead-free solder pastes application in automotive electronics. , 2014, , .		8
8	PCBs thermophysical properties in lead-free assembling process assessment. , 2010, , .		7
9	Methods for pads thermophysical parameters assessment in terms of 4P Soldering Model. , 2011, , .		6
10	Physical and Quantitative Microstructural Analysis of Sintered Al-Cu/SiCp Composites. Materials Science Forum, 2011, 672, 251-254.	0.3	5
11	Solder joints properties as function of multiple reflow Vapor Phase Soldering process. , 2012, , .		5
12	Vitroceramic coatings on metallic supports with biomedical applications. International Journal of Materials and Product Technology, 2000, 15, 446.	0.2	4
13	Preparation and Characterisation of Biocompatible Vitroceramic–Metal Systems for Applications in Medicine. Surface Engineering, 2001, 17, 313-316.	2.2	4
14	Investigation on thermal properties of substrates for printed electronics. , 2014, , .		4
15	Studies on thermal properties of substrates for electronics using IR thermography. , 2014, , .		4
16	A Model of Optimization and Control the Thermite Kit for Aluminothermic Welding. Solid State Phenomena, 0, 254, 83-90.	0.3	4
17	Aspects on thermophisycal properties of interconnection structures for power LEDs applications. , 2015, , .		3
18	Influence of high temperature exposure on the adhesion of a micro-composite refractory enamel to a Ni–18Cr–12W superalloy. Journal of Adhesion Science and Technology, 2017, 31, 2555-2570.	2.6	3

#	Article	IF	CITATIONS
19	Comparative shear tests of two low melting point solder pastes relating to their thermal diffusivity. , 2017, , .		3
20	Microstructure comparative analysis of the solder joints based on SAC/SN100 soldering alloy type depending on the cooling rate. , 2012, , .		2
21	Multiconvolutional approach for uncertainty estimation of the thermal diffusivity measured by flash method. , 2013, , .		2
22	Lead/lead-free solder alloys shear tests correlations with structure at different temperatures. , 2014, , .		2
23	Shear strength function of temperature for lead/lead-free alloys samples obtained with different cooling rate. , 2015, , .		2
24	Thermophysical properties of some Low Temperature Lead-Free solder pastes dedicated to automotive applications. , 2016, , .		2
25	Investigations Related to Electrically Conductive Adhesives Pastes Usage on SMT Lines. , 2018, , .		2
26	Pack-Aliting in Thermitic Powder Mixture Obtained by Mechanical Alloying. Revista De Chimie (discontinued), 2018, 69, 2092-2096.	0.4	2
27	Hardening of copper surfaces by beryllium diffusion. International Journal of Materials and Product Technology, 2002, 17, 659.	0.2	1
28	Solder joints properties assessment in the terms of 4P Soldering Model. , 2011, , .		1
29	A Study on Metal-Ceramic Thermal Expansion Compatibility. Solid State Phenomena, 2014, 216, 85-90.	0.3	1
30	Thermophysical Properties in Assembling Process at Macro and Micro Level. Advanced Materials Research, 2015, 1114, 172-179.	0.3	1
31	Properties Investigations on Copper Based Printed Conductive Pastes Electrical Joints. , 2018, , .		1
32	Thermal Investigations on Modules Realized Using Solderless Assembly for Electronics Technology. , 2019, , .		1
33	New Approach for Chemical Homogeneity Analysis of an AISI 316L Stainless Steel Bar Batch. Revista De Chimie (discontinued), 2018, 69, 1079-1083.	0.4	1
34	The Influence of the High Temperatures Thermal Shocks on the Microstructure and Harness of Zircaloy-4 alloy. Revista De Chimie (discontinued), 2018, 69, 1655-1660.	0.4	1
35	A New Robust Top-Down Method for Measurement Uncertainty Estimation of the ED(P)- XRFS Outcomes Carried on a Fluorescence Glass. Revista De Chimie (discontinued), 2018, 69, 2487-2493.	0.4	1
36	The Influence of Thermal Shocks on the Thermophisics Properties of the Zircaloy-4. Revista De Chimie (discontinued), 2019, 70, 575-577.	0.4	1

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37	Effect of Local Heating on the Mechanical Characteristics of Repaired Automotive Panels. Materiale Plastice, 2019, 56, 750-758.	0.8	1
38	Investigations at the Interface of a Multilayer Structure Made of Non-Conductive and Conductive Resins. , 2020, , .		1
39	Sulfonitrocarburizing of High-Speed Steel Cutting Tools: Kinetics and Performances. Materials, 2021, 14, 7779.	2.9	1
40	HISOLD 4P Q&R, COST project for solder material innovations and solder joint properties assessment. , 2009, , .		0
41	Low silver, lead free solder paste, new alloy developments. , 2010, , .		0
42	Complex Characterization of a New Low Ni Maraging Steel with Enhance Service Stability. Solid State Phenomena, 2012, 188, 346-351.	0.3	0
43	New approach for measuring the surface tension of SnAgCu305 molten alloy. , 2012, , .		Ο
44	The mischmetal and Bi <inf>94</inf> Zn <inf>6</inf> effect alloying on SACX 0307. , 2013, , .		0
45	Implant Surface Finishing Influence on Tissue-Implant Anchoring. Solid State Phenomena, 2014, 216, 39-44.	0.3	Ο
46	Correlation between Microstructure and Magnetic Properties on MnZn Ferrite with Bi <sub>2</sub> O <sub>3</sub> Increasing Addition. Solid State Phenomena, 2014, 216, 23-28.	0.3	0
47	Typical defects caused by untypical situations from assembling lines analysis. , 2015, , .		Ο
48	Thermodynamics of Iron Metallothermy. Advanced Materials Research, 0, 1114, 112-117.	0.3	0
49	Comparative shear tests of some low temperature lead-free solder pastes. , 2016, , .		Ο
50	Low Rigidity Ti-Nb-Ta-X (X=Cr, Zr, Ag, In) Alloys with Improved Properties. Key Engineering Materials, 2016, 695, 157-163.	0.4	0
51	Microstructure morphology of no-clean lead-free solder alloys used in automotive industry. , 2017, , .		0
52	Pressure Influence on the AlCrFeNiMn/Graphite High Entropy Composite Microhardness. Key Engineering Materials, 0, 750, 9-14.	0.4	0
53	Mechanical vs. Electrical Properties of Conductive Adhesive Bonds as Function of Operating Temperature. , 2019, , .		0
54	Electrically Conductive Paste Printed Volume Influence on Bonds Properties. , 2019, , .		0

 ${\it Electrically\ Conductive\ Paste\ Printed\ Volume\ Influence\ on\ Bonds\ Properties.\ ,\ 2019,\ ,\ .}$ 54

#	Article	IF	CITATIONS
55	On the Increase of the Current Carrying Capability of the Conductor Tracks Made of Electrically Conductive Adhesives. , 2021, , .		0
56	The Effects of Modifying the Activity of Nitriding Media by Diluting Ammonia with Nitrogen. Materials, 2021, 14, 2432.	2.9	0
57	Thermal Cycling Influence on the Transformation Characteristics of a Ni50Ti48Nb2 Shape Memory Alloy. Revista De Chimie (discontinued), 2017, 68, 991-996.	0.4	Ο
58	Non-Toxic Environment for Ferritic Nitrocarburising Process. Revista De Chimie (discontinued), 2018, 69, 2416-2419.	0.4	0
59	Mechanical properties of LEDs bonds realized with conductive adhesives paste. , 2018, , .		Ο
60	Activity modification of a new type of carbamide-based non-polluting solid powdery medium used in the sulphonitrocarburising process. International Journal of Surface Science and Engineering, 2020, 14, 307.	0.4	0
61	Obtaining the Controlled Sulphonitrocarburized Layer Phase Compositions, by the Variation of the Solid Powdery Medium Components. Revista De Chimie (discontinued), 2020, 71, 225-233.	0.4	0
62	A new approach for quantifying thermal barrier effect. Case study: RE_20 enamel. INCAS Bulletin, 2020, 12, 183-194.	0.6	0
63	Activity modification of a new type of carbamide-based non-polluting solid powdery medium used in the sulphonitrocarburising process. International Journal of Surface Science and Engineering, 2020, 14, 307.	0.4	0
64	Vibration Testing of a Solderless Electronic Module Manufactured by Additive Technique. , 2021, , .		0
65	Nitriding in ammonia-nitrogen gaseous mixtures, after the simultaneous saturation with Ti and Al. International Journal of Surface Science and Engineering, 2022, 16, 17.	0.4	О